

RECEIPT

PATENT APPLICATION

THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Jun-ichiro FURIHATA et al.

Application No.: 09/787,038

Docket No.: 108868

Filed: March 13, 2001

For: - METHOD OF PRODUCING A BONDED WAFER AND THE BONDED WAFER

REQUEST FOR CORRECTION OF PALM RECORDS **RECEIVED**

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Sir:

Attached is a photocopy of the original filing receipt on which errors have been corrected in red. These errors are being brought to the attention of the Patent and Trademark Office so that it may correct its records.

Respectfully submitted,

William P. Berridge
Registration No. 30,024

Thomas J. Pardini
Registration No. 30,411

Date: June 20, 2001

OLIFF & BERRIDGE, PLC
P.O. Box 19928
Alexandria, Virginia 22320
Telephone: (703) 836-6400

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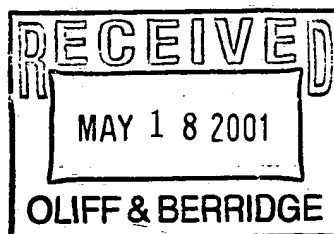
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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/787,038	03/13/2001	1746	1100	108868	4	18	16

CONFIRMATION NO. 8734

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 PO Box 19928
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FILING RECEIPT



Date Mailed: 05/11/2001

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Jun-ichiro Furihata, Gunma, JAPAN;
 Kiyoshi Mitani, Gunma, JAPAN;

Assignment for Published Patent Application
 SHIN-ETSU HANDOTAI CO., LTD.

Domestic Priority data as claimed by applicant

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Foreign Applications

JAPAN 11-201585 07/15/1999

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Non-Publication Request: No

Early Publication Request: No

Title

of A the
 Method for producing bonded wafer and bonded wafer

Preliminary Class

216

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